Advanced Packaging for Heterogeneous Integration: What’s Next
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New packaging solutions are being adopted to achieve the economic advantages that were previously met with silicon scaling. The role of heterogeneous integration, especially chiplets, is pivotal in this new era. Options include advanced fan-out, RDL interposer, embedded bridges, and 3D packaging. This presentation provides insight into some of the applications driving the use of chiplets and explores challenges in bringing this into HVM. The strategic role of materials is discussed.
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E. Jan Vardaman is president and founder of TechSearch International, Inc., which has provided market research and technology trend analysis in semiconductor packaging since 1987. She is the author of numerous publications on emerging trends in semiconductor packaging and assembly. She is a senior member of IEEE EPS and is an IEEE EPS Distinguished Lecturer. She received the IMAPS GBC Partnership award in 2012, the Daniel C. Hughes, Jr. Memorial Award in 2018, the Sidney J. Stein International Award in 2019, and she is an IMAPS Fellow. Before founding TechSearch International, she served on the corporate staff of Microelectronics and Computer Technology Corporation (MCC), the electronics industry's first pre-competitive research consortium.